

DESCRIPTION

The 82S140 and 82S141 are field programmable, which means that custom patterns are immediately available by following the fusing procedure given in this data sheet. The standard 82S140 and 82S141 are supplied with all outputs at logical low. Outputs are programmed to a logic high level at any specified address by fusing a Ni-Cr link matrix.

These devices include on-chip decoding and 4 chip enable inputs for ease of memory expansion. They feature either open collector or tri-state outputs for optimization of word expansion in bused organizations.

Both 82S140 and 82S141 devices are available in the commercial and military temperature ranges. For the commercial temperature range (0°C to +75°C) specify N82S140/141, F, and for the military temperature range (-55°C to +125°C) specify S82S140/141, F.

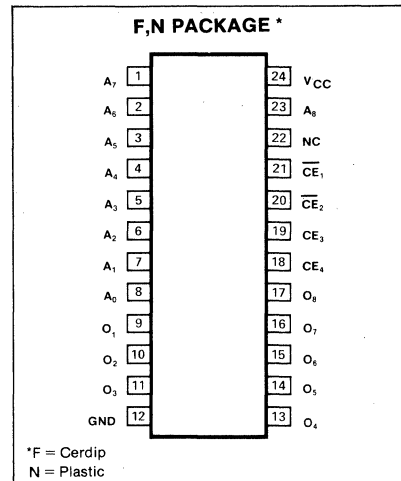
FEATURES

- **Address access time:**
N82S140/141: 60ns max
S82S140/141: 90ns max
- **Power dissipation:** .17mW/bit typ
- **Input loading:**
N82S140/141: -100µA max
S82S140/141: -150µA max
- **On-chip address decoding**
- **Output options:**
S82S140: Open collector
S82S141: Tri-state
- **No separate fusing pins**
- **Unprogrammed outputs are low level**
- **Fully TTL compatible**

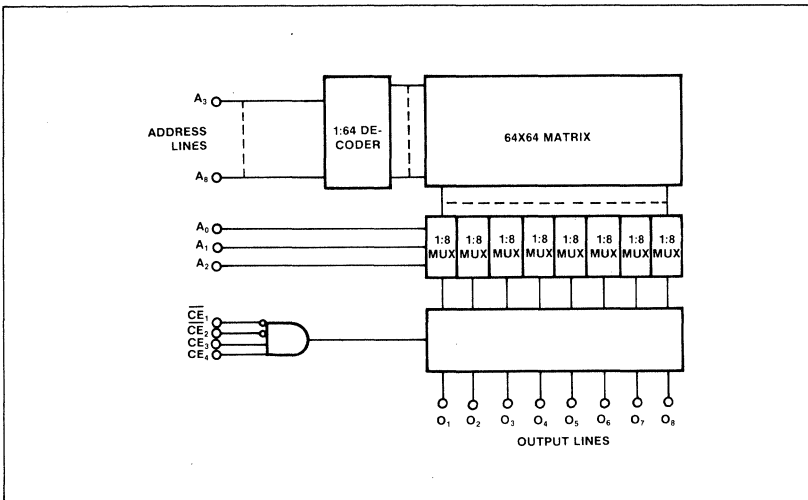
APPLICATIONS

- Prototyping/volume production
- Sequential controllers
- Microprogramming
- Hardwired algorithms
- Control store
- Random logic
- Code conversion

PIN CONFIGURATION



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
V _{CC} Supply voltage	+7	Vdc
V _{IN} Input voltage	+5.5	Vdc
Output voltage		Vdc
V _{OH} High (82S140)	+5.5	
V _O Off-state (82S141)	+5.5	
Temperature range		°C
T _A Operating		
N82S140/141	0 to +75	
S82S140/141	-55 to +125	
T _{STG} Storage	-65 to +150	

DC ELECTRICAL CHARACTERISTICS N82S140/141: 0°C ≤ T_A ≤ +75°C, 4.75V ≤ V_{CC} ≤ 5.25V
 S82S140/141: -55°C ≤ T_A ≤ +125°C, 4.5V ≤ V_{CC} ≤ 5.5V

PARAMETER	TEST CONDITIONS ¹	N82S140/141			S82S140/141			UNIT
		Min	Typ ²	Max	Min	Typ ²	Max	
V _{IL} V _{IH} V _{IC}	Input voltage Low High Clamp I _{IN} = -18mA	2.0	-0.8	.85 -1.2	2.0	-0.8	.80 -1.2	V
V _{OL} V _{OH}	Output voltage Low High (82S141) I _{OUT} = 9.6mA CE ₁ = Low, I _{OUT} = -2mA, CE ₂ = Low, CE ₃ = High, CE ₄ = High, High stored	2.4		0.45	2.4		0.5	V
I _{IL} I _{IH}	Input current Low High V _{IN} = 0.45V V _{IN} = 5.5V			-100 40			-150 50	μA
I _{OLK}	Output current Leakage (82S140) CE ₁ = High, V _{OUT} = 5.5V, CE ₂ = High, CE ₃ = Low, CE ₄ = Low			40			60	μA
I _{O(OFF)}	Hi-Z state (82S141) CE ₁ = High, V _{OUT} = 0.5V, CE ₂ = High, CE ₃ = Low, CE ₄ = Low			-40			-60	μA
I _{OS}	Short circuit (82S141) CE ₁ = High, V _{OUT} = 5.5V, CE ₂ = High, CE ₃ = Low, CE ₄ = Low V _{OUT} = 0V	-20		-70	-15		-85	mA
I _{CC}	V _{CC} supply current		140	175		140	185	mA
C _{IN} C _{OUT}	Capacitance Input Output V _{CC} = 5.0V V _{IN} = 2.0V V _{OUT} = 2.0V		5 8			5 8		pF

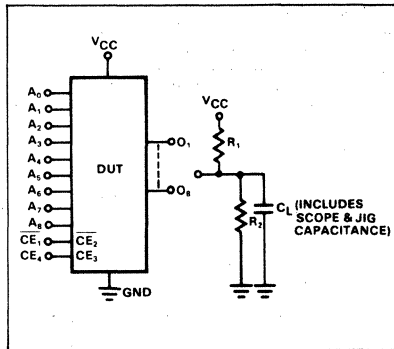
AC ELECTRICAL CHARACTERISTICS R₁ = 470Ω, R₂ = 1kΩ, C_L = 30pF
 N82S140/141: 0°C ≤ T_A ≤ +75°C, 4.75V ≤ V_{CC} ≤ 5.25V
 S82S140/141: -55°C ≤ T_A ≤ +125°C, 4.5V ≤ V_{CC} ≤ 5.5V

PARAMETER	TO	FROM	N82S140/141			S82S140/141			UNIT
			Min	Typ ²	Max	Min	Typ ²	Max	
T _{AA} T _{CE}	Access time Output Output	Address Chip enable		40 20	60 40		40 20	90 50	ns
T _{CD}	Disable time Output	Chip disable		20	40		20	50	ns

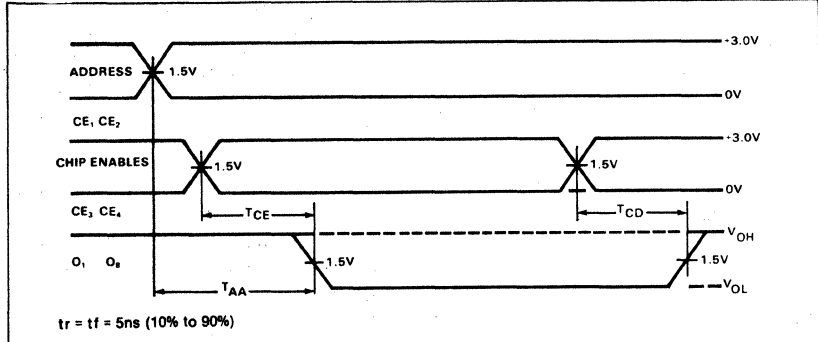
NOTES

1. Positive current is defined as into the terminal referenced.
2. Typical values are at V_{CC} = 5.0V, T_A = +25°C.

TEST LOAD CIRCUIT



VOLTAGE WAVEFORM



PROGRAMMING SYSTEMS SPECIFICATIONS (Testing of these limits may cause programming of device.) $T_A = +25^\circ C$

PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ	Max	
V_{CCP} Power supply voltage To program ¹	$I_{CCP} = 375 \pm 75mA$, Transient or steady state	8.5	8.75	9.0	V
V_{CCH} Verify limit Upper		5.3	5.5	5.7	V
V_{CCL} Lower		4.3	4.5	4.7	V
V_S Verify threshold ²		1.4	1.5	1.6	V
I_{CCP} Programming supply current	$V_{CCP} = +8.75 \pm .25V$	300		450	mA
V_{IH} Input voltage High		2.4		5.5	V
V_{IL} Low		0	0.4	0.8	V
I_{IH} Input current High	$V_{IH} = +5.5V$			50	μA
I_{IL} Low	$V_{IL} = +0.4V$			-500	μA
V_{OUT} Output programming voltage ³	$I_{OUT} = 200 \pm 20mA$, Transient or steady state	16.0	17.0	18.0	V
I_{OUT} Output programming current	$V_{OUT} = +17 \pm 1V$	180	200	220	mA
T_R Output pulse rise time		10		50	μs
t_p CE programming pulse width		0.3	0.4	0.5	ms
t_D Pulse sequence delay		10			μs
T_{PR} Programming time	$V_{CC} = V_{CCP}$			12	sec
T_{PSI} Initial programming pause	$V_{CC} = 0V$	6			sec
$\frac{T_{PR}}{T_{PR}+T_{PS}}$ Programming duty cycle ⁴				50	%
FL Fusing attempts per link				2	cycle

NOTES

1. Bypass V_{CC} to GND with a $0.01\mu F$ capacitor to reduce voltage spikes.
2. V_S is the sensing threshold of the PROM output voltage for a programmed bit. It normally constitutes the reference voltage applied to a comparator circuit to verify a successful fusing attempt.
3. Care should be taken to insure the $17 \pm 1V$ output voltage is maintained during the entire fusing cycle.
4. Programming duty cycle is 50% after continuous programming at 100% duty cycle.
5. This is an updated method of programming and does not obsolete any programming systems presently being used.

PROGRAMMING PROCEDURE

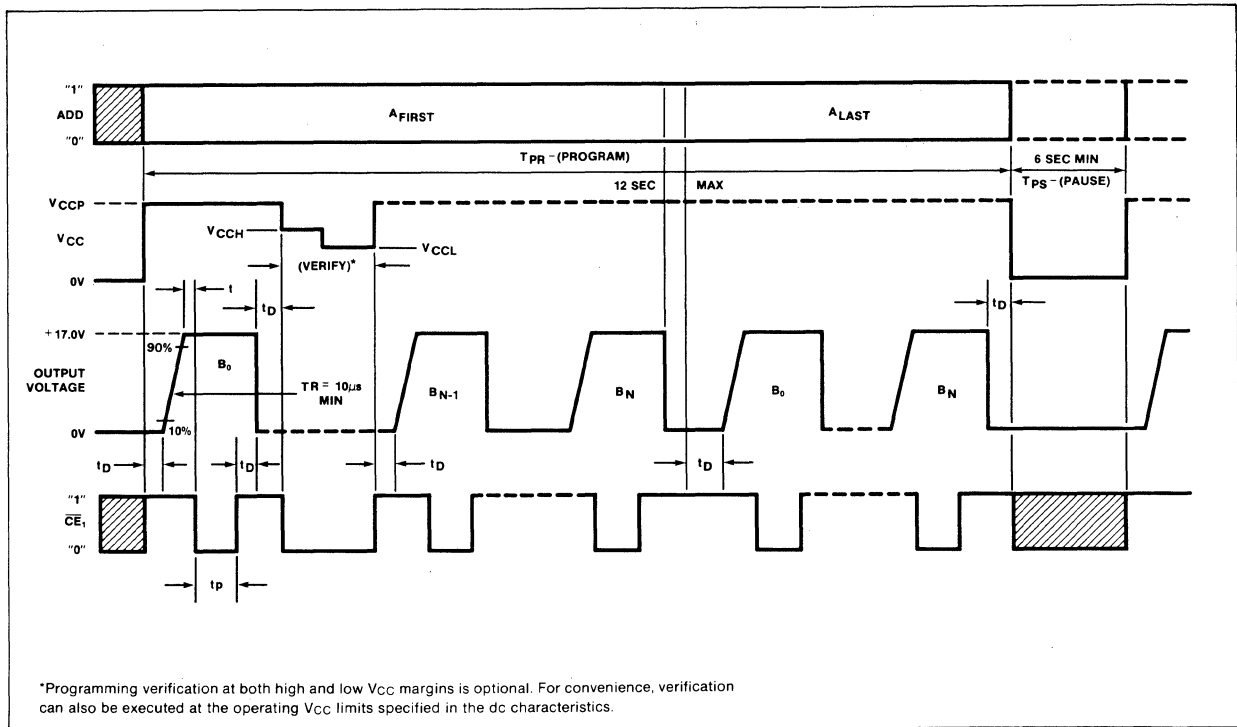
1. Terminate all device outputs with a 10kΩ resistor to V_{CC}. Apply $\overline{CE}_1 = \text{High}$, $\overline{CE}_2 = \text{Low}$, $\overline{CE}_3 = \text{High}$ and $\overline{CE}_4 = \text{High}$.
2. Select the Address to be programmed, and raise V_{CC} to V_{CCP} = 8.75 ± .25V.
3. After 10μs delay, apply V_{OUT} = +17 ± 1V to the output to be programmed. Program one output at the time.

4. After 10μs delay, pulse the \overline{CE}_1 input to logic low for 0.3 to 0.5ms.
5. After 10μs delay, remove +17V from the programmed output.
6. To verify programming, after 10μs delay, lower V_{CC} to V_{CCH} = +5.5 ± .2V, and apply a logic low level to the CE input. The programmed output should remain in the high state. Again, lower V_{CC} to V_{CCL} =

+4.5 ± .2V, and verify that the programmed output remains in the high state.

7. Raise V_{CC} to V_{CCP} = 8.75 ± .25V, and repeat steps 3 through 6 to program other bits at the same address.
8. After 10μs delay, repeat steps 2 through 7 to program all other address locations.

TYPICAL PROGRAMMING SEQUENCE



BIPOLAR MEMORY